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# INTRODUCTION

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Fig. 1. Magnetization as a function of applied field. Note that “Fig.” is abbreviated. There is a period after the figure number, followed by two spaces. It is good practice to explain the significance of the figure in the caption.

TABLE I

Units for Magnetic Properties

|  |  |  |
| --- | --- | --- |
| Symbol | Quantity | Conversion from Gaussian and  CGS EMU to SI a |
| Φ | magnetic flux | 1 Mx → 10−8 Wb = 10−8 V·s |
| *B* | magnetic flux density,  magnetic induction | 1 G → 10−4 T = 10−4 Wb/m2 |
| *H* | magnetic field strength | 1 Oe → 103/(4π) A/m |
| *m* | magnetic moment | 1 erg/G = 1 emu  → 10−3 A·m2 = 10−3 J/T |
| *M* | magnetization | 1 erg/(G·cm3) = 1 emu/cm3  → 103 A/m |
| 4π*M* | magnetization | 1 G → 103/(4π) A/m |
| σ | specific magnetization | 1 erg/(G·g) = 1 emu/g → 1 A·m2/kg |
| *j* | magnetic dipole  moment | 1 erg/G = 1 emu  → 4π × 10−10 Wb·m |
| *J* | magnetic polarization | 1 erg/(G·cm3) = 1 emu/cm3  → 4π × 10−4 T |
| χ*,* κ | susceptibility | 1 → 4π |
| χρ | mass susceptibility | 1 cm3/g → 4π × 10−3 m3/kg |
| μ | permeability | 1 → 4π × 10−7 H/m  = 4π × 10−7 Wb/(A·m) |
| μr | relative permeability | μ → μr |
| *w, W* | energy density | 1 erg/cm3 → 10−1 J/m3 |
| *N, D* | demagnetizing factor | 1 → 1/(4π) |

Vertical lines are optional in tables. Statements that serve as captions for the entire table do not need footnote letters.

aGaussian units are the same as cgs emu for magnetostatics; Mx = maxwell, G = gauss, Oe = oersted; Wb = weber, V = volt, s = second, T = tesla, m = meter, A = ampere, J = joule, kg = kilogram, H = henry.

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# Conclusion

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Appendixes, if needed, appear before the acknowledgment.

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